



Case: AMKOR-052A

#23/Amolte  
(not)  
7-25-03  
C. Moore

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Tae Heon Lee et al.	)	Group No.:	2814
Serial No.:	09/687,048	)		
Filed:	10/13/2000	)	Examiner:	Nguyen, Dilinh P.
For:	Leadframe and Semiconductor Package with Improved Solder Joint Strength	)		

M. Baunson  
9/26/03

AMENDMENT AFTER FINAL ACTION PURSUANT TO 37 C.F.R. § 1.116

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

Applicant acknowledges, with appreciation, the time taken by Examiner Nguyen to telephonically interview the present application with Applicant's counsel on July 8, 2003. As a result of this telephonic interview, Applicant respectfully requests that the present application be amended as follows:

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AF/2800  
PTO/SB/21 (08-00)

Approved for use through 10/31/2002. OMB 0651-0031  
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# TRANSMITTAL FORM

(to be used for all correspondence after initial filing)

		Application Number	09/687,048
		Filing Date	10/13/00
		First Named Inventor	Tae Heon Lee et al.
		Group Art Unit	2814
		Examiner Name	Dilinh P. Nguyen
Total Number of Pages in This Submission		Attorney Docket Number	AMKOR-052A

## ENCLOSURES (check all that apply)

<input type="checkbox"/> Fee Transmittal Form	<input type="checkbox"/> Assignment Papers (for an Application)	<input type="checkbox"/> After Allowance Communication to Group
<input type="checkbox"/> Fee Attached	<input type="checkbox"/> Drawing(s)	<input type="checkbox"/> Appeal Communication to Board of Appeals and Interferences
<input checked="" type="checkbox"/> Amendment / Reply	<input type="checkbox"/> Licensing-related Papers	<input type="checkbox"/> Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)
<input checked="" type="checkbox"/> After Final	<input type="checkbox"/> Petition	<input type="checkbox"/> Proprietary Information
<input type="checkbox"/> Affidavits/declaration(s)	<input type="checkbox"/> Petition to Convert to a Provisional Application	<input type="checkbox"/> Status Letter
<input type="checkbox"/> Extension of Time Request	<input type="checkbox"/> Power of Attorney, Revocation Change of Correspondence Address	<input checked="" type="checkbox"/> Other Enclosure(s) (please identify below):
<input type="checkbox"/> Express Abandonment Request	<input type="checkbox"/> Terminal Disclaimer	<b>Certificate of Mailing, Return Receipt Postcard</b>
<input type="checkbox"/> Information Disclosure Statement	<input type="checkbox"/> Request for Refund	
<input type="checkbox"/> Certified Copy of Priority Document(s)	<input type="checkbox"/> CD, Number of CD(s) _____	
<input type="checkbox"/> Response to Missing Parts/ Incomplete Application		
<input type="checkbox"/> Response to Missing Parts under 37 CFR 1.52 or 1.53		
Remarks		

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## SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

Firm or Individual name	Mark B. Garred STETINA BRUNDA GARRED & BRUCKER
Signature	
Date	7/9/03

## CERTIFICATE OF MAILING

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Typed or printed name	Andrea K. Treitler
Signature	
Date	7/9/03

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AUTORNEY DOCKET NO: AMKOR-052A  
TITLE: LEAD FRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED  
SOLDER JOINT STRENGTH

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on July 9, 2003

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